

Power devices / Cooling plates

Analysing voiding and soldered area of assembled power devices and cooling plates. Special solder-level separation technique for multi-layer soldering applications (hybrid-power components).

Inspection coverage (extract):

- Voiding [%]
- Voiding (area)
- Void-separation for multi-layer (i.ex. for chip-layer and substrate layer)
- Soldering area

Requires high power setup and 16 Bit detector technology for heavy cooling plates. By using the MatriX [SFT™ Technology](#) - inhomogeneous backgrounds and disturbing structures are eliminated, thus assuring a correct void calculation.

Product Family



X series

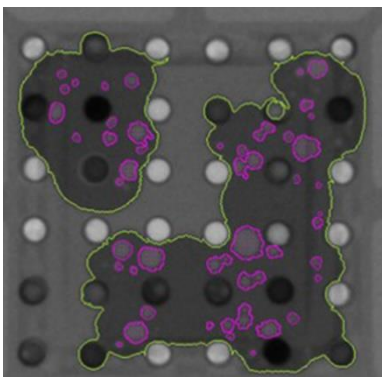


X# series

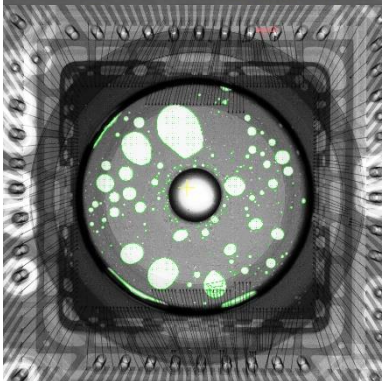


XT series

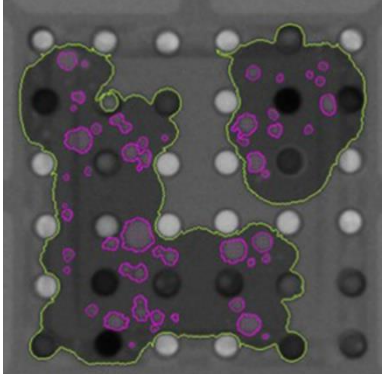
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